



AMD Instinct MI455X

CDNA 5

EAM

2026

TSMC 2nm/3nm

OVERVIEW

315.0 FP32 TFLOPS	432 GB Memory HBM4	23.3 TB/s Memory Bandwidth	— TDP
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PERFORMANCE METRICS

Precision	Peak (dense)	2:4 Sparse	Bits	Type
FP64	5.0	N/A	64	Standard
FP32	315.0	N/A	32	Standard
TF32	—	not published	—	Standard
BF16	5033.0	10066.0	16	Standard
FP16	5033.0	10066.0	16	Standard
FP8	20133.0	not published	8	Standard
FP6	20133.0	not published	—	Standard
FP4	40265.0	not published	4	Standard
INT8	5033.0	10066.0	8	Standard

MEMORY SPECIFICATIONS

Capacity	432 GB
Type	HBM4
Bandwidth	23.3 TB/s
Interface Width	—

POWER & EFFICIENCY

TDP	—
Max power	—
FP32 dense TFLOPS per W of TDP	—
FP16 dense TFLOPS per W of TDP	—

Per W of TDP figures divide dense peak by accelerator TDP.
Board power only: excludes host CPUs, networking, cooling and facility overhead.

HARDWARE DETAILS

Vendor: AMD	Architecture: CDNA 5	Process Node: TSMC 2nm/3nm
Form Factor: EAM	Launch Year: 2026	

COMPUTE ENGINE

Work Group Processor: 256

ENTERPRISE FEATURES

Sparsity: **Yes**
